



## Material Content Data Sheet



<b>Sales Product Name</b>				IPD90N10S4L-06		<b>Issued</b>		4. July 2019	
<b>MA#</b>				MA003587332					
<b>Package</b>				PG-TO252-3-313		<b>Weight*</b>		319.92 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.425	1.38	1.38	13833	13833	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
	non noble metal	iron	7439-89-6	0.147	0.05		460		
	non noble metal	copper	7440-50-8	147.096	45.99	46.05	459787	460385	
	non noble metal	aluminium	7429-90-5	4.502	1.41	1.41	14072	14072	
wire	non noble metal	aluminium	7429-90-5	4.502	1.41	1.41	14072	14072	
encapsulation	organic material	carbon black	1333-86-4	1.359	0.42		4247		
	plastics	epoxy resin	-	23.779	7.43		74328		
	inorganic material	silicondioxide	60676-86-0	110.743	34.62	42.47	346156	424731	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11690	11690	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4440	4451	
solder	non noble metal	tin	7440-31-5	0.069	0.02		216		
	noble metal	silver	7440-22-4	0.087	0.03		270		
	non noble metal	lead	7439-92-1	3.305	1.03	1.08	10330	10816	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		60		
	non noble metal	copper	7440-50-8	19.177	5.99	6.00	59944	60022	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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